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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of
SHIVKUMAR, Bharat et al

New York, New York
Date: March 5, 2004
Group Art Unit: 2827

Serial No.: 09/812,027

Date Filed: March 19, 2001

For: SEMICONDUCTOR MULTICHIP MODULE PACKAGE WITH IMPROVED THERMAL
PERFORMANCE; REDUCED SIZE AND IMPROVED MOISTURE RESISTANCE

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

STATUS INQUIRY LETTER

Sir:

Our records indicate that we filed a response to an Office Action in the above-identified application about six months ago.

Since that response, we have not received any communication from the U.S. Patent Office.
Kindly advise us of the status of this application.

Respectfully Submitted,

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